

## **AMENDMENTS TO THE SPECIFICATION**

Please amend Paragraph 0011 on page 5 of the Specification as set forth below:

[0011] Referring to FIGS. 1 and 2, the configuration and alignment of the power and ground connectors 40 and 42 are likely to provide better electrical performance, such as common mode noise reduction, to enhance signal integrity performance. The power and ground socket connectors ~~42 and 44~~ 40 and 42 may be configured and oriented to obtain symmetry about the imaginary geometric plane bisecting the distance between the connectors ~~42 and 44~~ 40 and 42, such plane being substantially perpendicular to the top surface 26 of the PCB 14 and the bottom surface 22 of the IC package 12. Hence, the broadside portion 44 and 46 are substantially parallel to the geometric plane. Because the areas of the broadside portions 44 and 46 of the connectors 40 and 42, respectively, are facing each other in a spaced-apart adjacent relationship and are in relatively close proximity, enhanced noise reduction may be obtained without additional structures or manufacturing processes. The distance between the broadside portions 44 and 46 may be less than a 1 millimeter and the distance from center-to-center of the two solder balls 28 in FIG. 2 may be about 1 to 1.2 millimeters. By having the two arcuate arm portions 52 and 54 extend outwardly from the geometric plane in opposite directions and the two bracket portions 56 and 58 extending outwardly from the geometric plane in opposite directions, such directions being substantially perpendicular to the geometric plane, the distance between the two broadside portions 44 and 46 may be reduced. The bottom surface 22 of the IC package 12 may be disposed in a spaced-apart, substantially parallel relationship to the top surface 26 of the PCB 14; hence, both surfaces may be substantially perpendicular to the geometric plane bisecting the power and ground connectors ~~42 and 44~~ 40 and 42. In summary, the socket 10, in accordance to one embodiment of the present invention shown in FIGS. 1 and 2, may provide the following technical advantages. The symmetrical pairs of power and ground connectors 40 and 42 result in reduced common mode noise. The symmetrical connector pairs have closer opposed broadside portions 44 and 46 and, as a result, reduced socket pin loop inductance may be achieved.